

Title (en)

METHODS FOR ELECTROLYTICALLY DEPOSITING PRETREATMENT COMPOSITIONS

Title (de)

VERFAHREN ZUR ELEKTROLYTISCHEN ABSCHIEDUNG VON VORBEHANDLUNGSZUSAMMENSETZUNGEN

Title (fr)

PROCÉDÉS DE DÉPÔT ÉLECTROLYTIQUE DE COMPOSITIONS DE PRÉTRAITEMENT

Publication

**EP 4061986 A1 20220928 (EN)**

Application

**EP 20829053 A 20201123**

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Abstract (en)

[origin: WO2021102413A1] Methods for treating a substrate are disclosed. A method includes contacting a substrate with a pretreatment composition comprising a Group IVB metal and an electropositive metal and passing an electric current between an anode and the substrate serving as a cathode to deposit a coating from the pretreatment composition on the substrate. A method for treating an electrically conductive substrate also includes contacting the electrically conductive substrate with a pretreatment composition comprising a Group IVB metal and an electropositive metal and electrodepositing a coating on the electrically conductive substrate from the pretreatment composition. A method further includes contacting an electrically conductive substrate with a pretreatment composition comprising a Group IVB metal and an electropositive metal; and electrodepositing a coating on the electrically conductive substrate from the pretreatment composition, wherein the coating comprises each of the Group IVB metal and the electropositive metal.

IPC 8 full level

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